

Amendments to the Specification

*Please replace the paragraph before "BACKGROUND OF THE INVENTION" on page 1, line 3, by the following amended paragraph:*

Cross-Reference to Related Applications

This application is a continuation application of copending, commonly assigned Application No. 09/606,825, filed June 28, 2000, now U.S. Patent No. 6,593,843, the disclosure of which is incorporated herein by reference.

*Please replace the paragraph beginning at page 3, line 20 by the following amended paragraph.*

Additionally, an adhesion promoting layer such as a coupling agent can be used between the foil and the conductive element. The use of adhesion promoting layers in combination with foils having certain roughness characteristics is described in copending commonly assigned Application No. 09/606,821 (Becker et al.), now U.S. Patent No. 6,531,950, filed contemporaneously with this application, the disclosure of which is incorporated herein by reference.